



1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS.  
LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER.  
MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.  
PLACE BOARD STANDOFFS X1, X2, X3, X4 AT 4 CORNER LOCATIONS.
3. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT  
TABS ON FOUR SIDES OF THE BOARD EDGE.
4. ASSY PROCESSES SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD.